



UAT

KEY SERVICES

- Gold bumping
- Electroplated solder bumping
- Electroplated copper pillar bumping
- Large solder bumping (ball drop)
- PBO, Polyimides & BCB passivation
- Redistribution of bond pads
- In-house photomask & stencil design capability

WAFER BUMPING MARKET DRIVERS

- Small footprint (> 5x reduction)
- Reduced weight (> 5x reduction)
- Improved Electrical Conductivity, Thermal Dissipation and Inductance
- Widely used in hand-held devices such as mobile phones, tablets and the Internet of Things

KEY FACTS

- Linear/Analog
- 6" and 8" wafer bumping capability
- Equipment capacity: 20,000 wafers / month
- Factory Floor Space: 22,000 sq.ft.
- Class 1,000 and 10,000 Clean Rooms
- Over 100 different processing options to support your production requirements

CERTIFICATIONS

- ISO 14001:2004
- ISO 9001:2008
- ISO/TS 16949:2009
- Certificate of Green Partner (Sony)
- Samsung ECO Partner
- EICC VAP

